

L Number	Hits	Search Text	DB	Time stamp
-	306	451/526.ccls.	USPAT; US-PGPUB; EPO; JPO	2002/12/10 13:20
-	8820	(polish polishing planarize planarizing planarization) with (conduct conductive electrode electrodes)	USPAT; US-PGPUB; EPO; JPO	2002/12/10 11:37
-	1530	((polish polishing planarize planarizing planarization) with (conduct conductive electrode electrodes)) with (pad article body device)	USPAT; US-PGPUB; EPO; JPO	2002/12/10 11:38
-	814	((((polish polishing planarize planarizing planarization) with (conduct conductive electrode electrodes)) with (pad article body device)) with (substrate wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO	2002/12/10 11:39
-	142	451/\$.ccls. and pad with (conductive electrode)	USPAT; US-PGPUB; EPO; JPO	2002/12/10 19:40
-	183	polishing near2 pad with (conductive electrode)	USPAT; US-PGPUB; EPO; JPO	2002/12/10 19:41
-	15	("5222329" "5242524" "5308438" "5337015" "5413941" "5439551" "5738562" "5830041" "5876265" "5904608" "5944580" "5948700" "6007405" "6010538" "6015754").PN.	USPAT	2002/12/10 19:46
-	15	("5222329" "5242524" "5308438" "5337015" "5413941" "5439551" "5738562" "5830041" "5876265" "5904608" "5944580" "5948700" "6007405" "6010538" "6015754").PN.	USPAT	2002/12/10 19:51